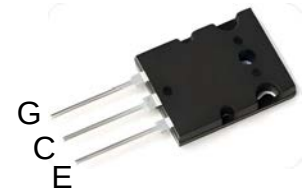




Features

- High speed switching
- Low saturation voltage : $V_{CE(sat)} = 2.1\text{ V}$ @ $I_C = 80\text{ A}$
- High input impedance
- CO-PAK, IGBT with FRD: $t_{rr} = 75\text{ nS}$ (typ.)



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Maxmim Ratings (Ta=25°Cunless otherwise noted)

Symbol	Description	SGL160N60UFD	Units
V_{CES}	Collector-Emitter Voltage	600	V
V_{GES}	Gate-Emitter Voltage	± 20	V
I_C	Collector Current @ $T_C = 25^\circ\text{C}$	160	A
	Collector Current @ $T_C = 100^\circ\text{C}$	80	A
$I_{CM(1)}$	Pulsed Collector Current	300	A
I_F	Diode Continuous Forward Current @ $T_C = 100^\circ\text{C}$	25	A
I_{FM}	Diode Maximum Forward Current	280	A
P_D	MaximumPowerDissipation @ $T_C = 25^\circ\text{C}$	250	W
	Maximum Power Dissipation @ $T_C = 100^\circ\text{C}$	100	W
T_J	Operating Junction Temperature	-55 to +150	$^\circ\text{C}$
T_{stg}	Storage Temperature Range	-55 to +150	$^\circ\text{C}$
T_L	Maximum Lead Temp. for Soldering Purposes, 1/8" from Case for 5 Seconds	300	$^\circ\text{C}$

Notes :

(1) Repetitive rating : Pulse width limited by max. junction temperature

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}(\text{IGBT})$	Thermal Resistance, Junction-to-Case	--	0.5	$^\circ\text{C/W}$
$R_{\theta JC}(\text{DIODE})$	Thermal Resistance, Junction-to-Case	--	0.83	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	--	25	$^\circ\text{C/W}$



Electrcal Charcteristics Ta=25°C unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
Off Characteristics						
BV _{CES}	Collector-Emitter Breakdown Voltage	V _{GE} = 0V, I _C = 250uA	800	--	--	V
ΔB _{V_{CES}} /ΔT _J	Temperature Coefficient of Breakdown Voltage	V _{GE} = 0V, I _C = 1mA	--	0.9	--	V/°C
I _{CES}	Collector Cut-Off Current	V _{CE} = V _{CES} , V _{GE} = 0V	--	--	250	uA
I _{GES}	G-E Leakage Current	V _{GE} = V _{GES} , V _{CE} = 0V	--	--	± 100	nA
On Characteristics						
V _{GE(th)}	G-E Threshold Voltage	I _C = 50mA, V _{CE} = V _{GE}	4.5	5.4	6.5	V
V _{CE(sat)}	Collector to Emitter Saturation Voltage	I _C = 80A, V _{GE} = 15V	--	1.1	2.6	V
		I _C = 160A, V _{GE} = 15V	--	1.4	3.0	V
Dynamic Characteristics						
C _{ies}	Input Capacitance	V _{CE} = 30V, V _{GE} = 0V, f = 1MHz	--	5000	--	pF
C _{oes}	Output Capacitance		--	600	--	pF
C _{res}	Reverse Transfer Capacitance		--	200	--	pF
Switching Characteristics						
t _{d(on)}	Turn-On Delay Time	V _{CC} = 300 V, I _C = 80A, R _G = 3.9Ω, V _{GE} =15V Inductive Load, T _C = 25°C	--	40	--	ns
t _r	Rise Time		--	101	--	ns
t _{d(off)}	Turn-Off Delay Time		--	90	130	ns
t _f	Fall Time		--	75	150	ns
E _{on}	Turn-On Switching Loss		--	2500	--	uJ
E _{off}	Turn-Off Switching Loss		--	1760	--	uJ
E _{ts}	Total Switching Loss		--	4260	5000	uJ
t _{d(on)}	Turn-On Delay Time	V _{CC} = 300 V, I _C = 80A, R _G = 3.9Ω, V _{GE} = 15V Inductive Load, T _C = 125°C	--	45	--	ns
t _r	Rise Time		--	105	--	ns
t _{d(off)}	Turn-Off Delay Time		--	140	200	ns
t _f	Fall Time		--	122	250	ns
E _{on}	Turn-On Switching Loss		--	2785	--	uJ
E _{off}	Turn-Off Switching Loss		--	3100	--	uJ
E _{ts}	Total Switching Loss		--	5885	--	uJ
Q _g	Total Gate Charge	V _{CE} = 300 V, I _C = 80A, V _{GE} = 15V	--	345	520	nC
Q _{ge}	Gate-Emitter Charge		--	60	100	nC
Q _{gc}	Gate-Collector Charge		--	95	150	nC
L _e	Internal Emitter Inductance	Measured 5mm from PKG	--	18	--	nH

Electrcal Charcteristics of the Diode(Ta=25°C unless otherwise specified)

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Units
V _{FM}	Diode Forward Voltage	I _F = 25A	T _C = 25°C	--	1.4	1.7	V
			T _C = 100°C	--	1.3	--	
t _{rr}	Diode Reverse Recovery Time	I _F = 25A, di/ dt = 200 A/us	T _C = 25°C	--	95	150	ns
			T _C = 100°C	--	105	150	
I _{rr}	Diode Peak Reverse Recovery Current		T _C = 25°C	--	4.5	10	A
			T _C = 100°C	--	8.5	--	
Q _{rr}	Diode Reverse Recovery Charge		T _C = 25°C	--	152	375	nC
			T _C = 100°C	--	420	--	



Typical Characteristics

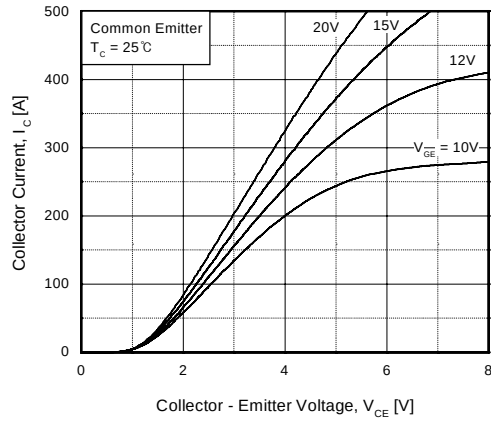


Fig 1. Typical Output Characteristics

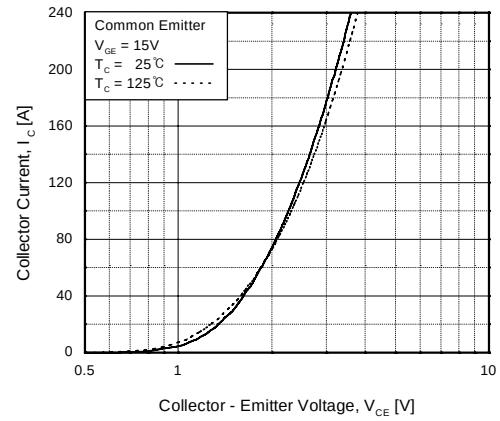


Fig 2. Typical Saturation Voltage Characteristics

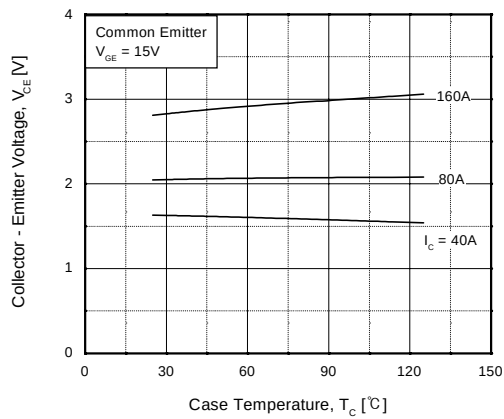


Fig 3. Saturation Voltage vs. Case Temperature at Variant Current Level

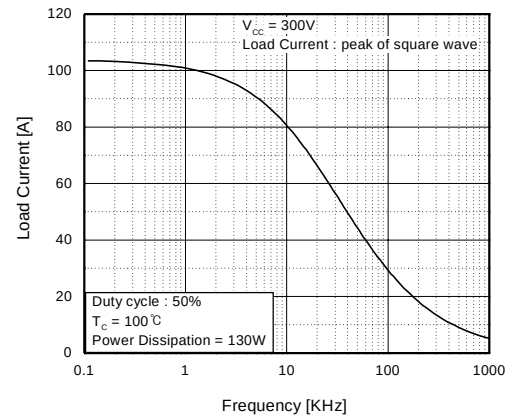


Fig 4. Load Current vs. Frequency

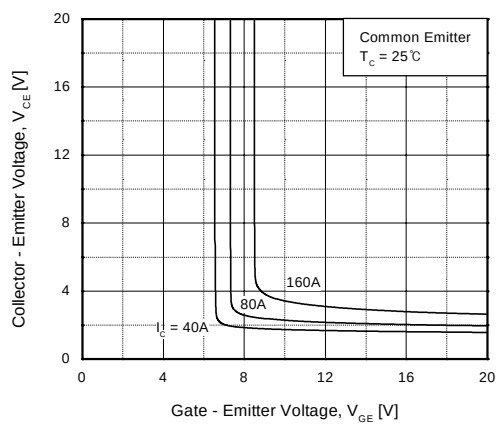


Fig 6. Saturation Voltage vs. V_{GE}

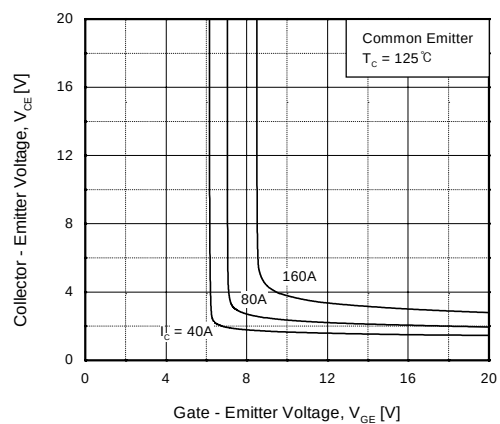


Fig 7. Saturation Voltage vs. V_{GE}

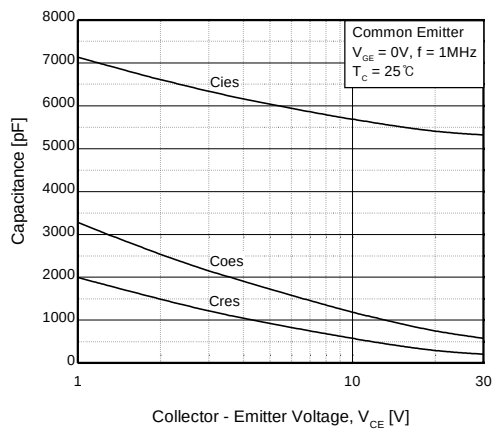


Fig 7. Capacitance Characteristics

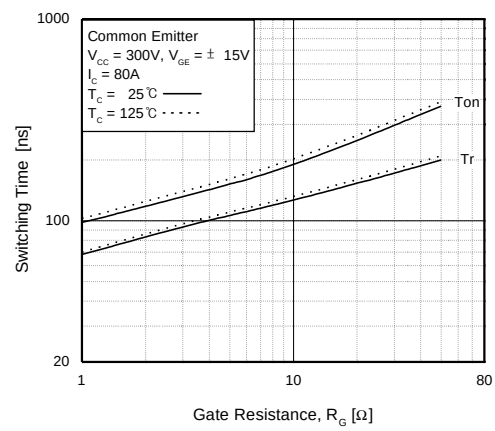


Fig 8. Turn-On Characteristics vs. Gate Resistance

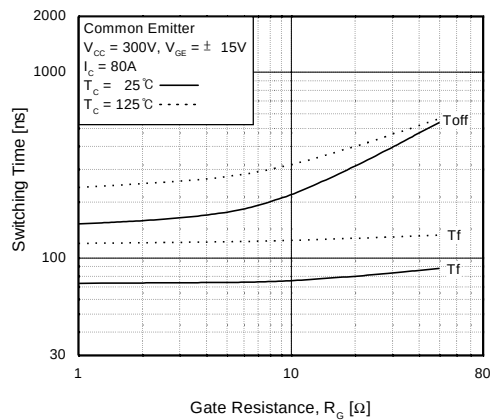


Fig 9. Turn-Off Characteristics vs. Gate Resistance

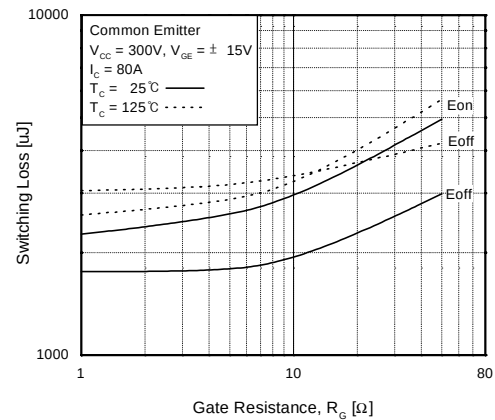


Fig 10. Switching Loss vs. Gate Resistance

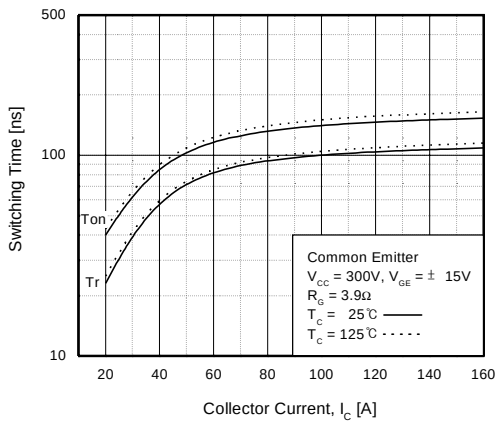


Fig 11. Turn-On Characteristics vs. Collector Current

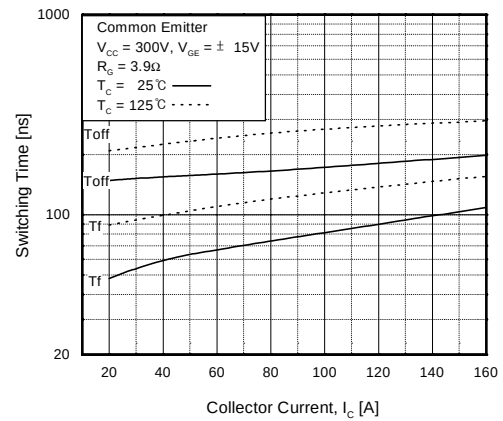


Fig 12. Turn-Off Characteristics vs. Collector Current

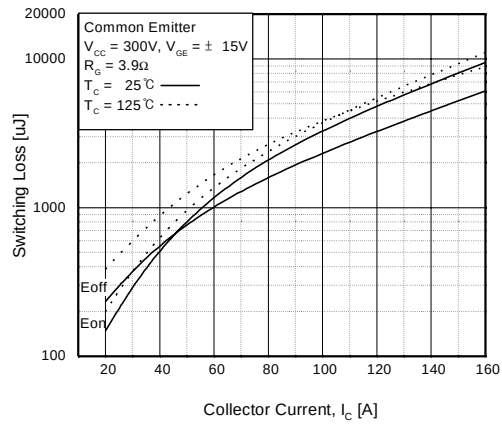


Fig 13. Switching Loss vs. Collector Current

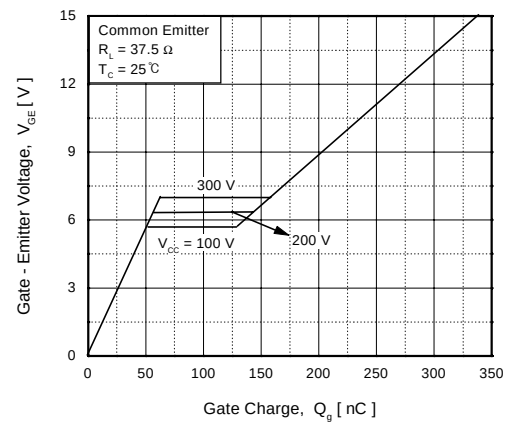


Fig 14. Gate Charge Characteristics

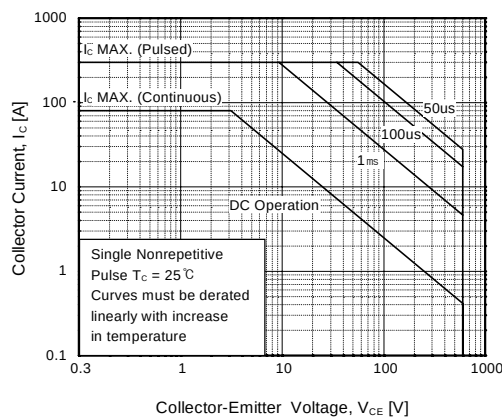


Fig 15. SOA Characteristic

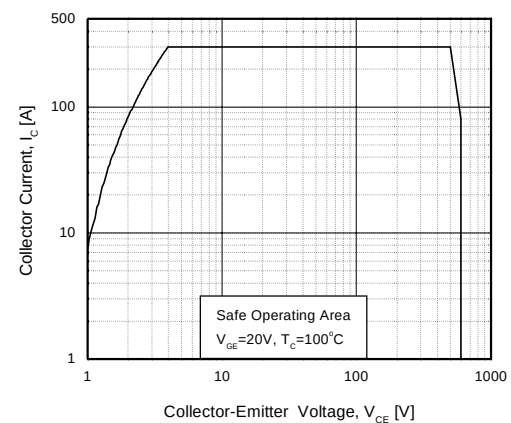


Fig 16. Turn-Off SOA Characteristics

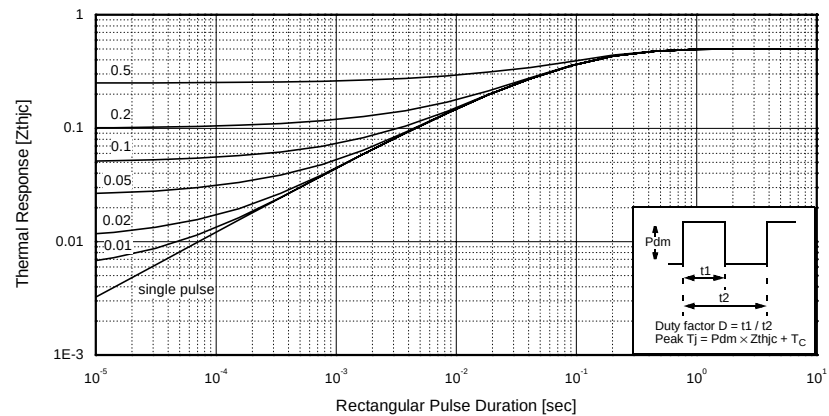


Fig 17. Transient Thermal Impedance of IGBT

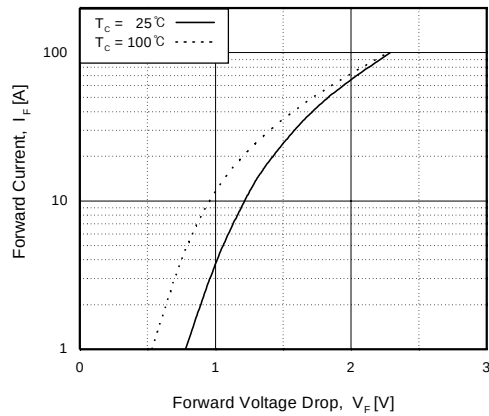


Fig 18. Forward Characteristics

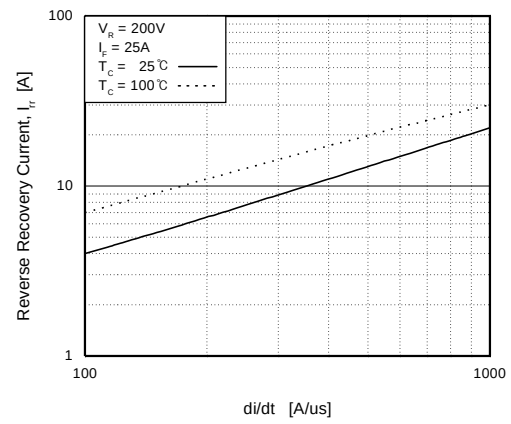


Fig 19. Reverse Recovery Current

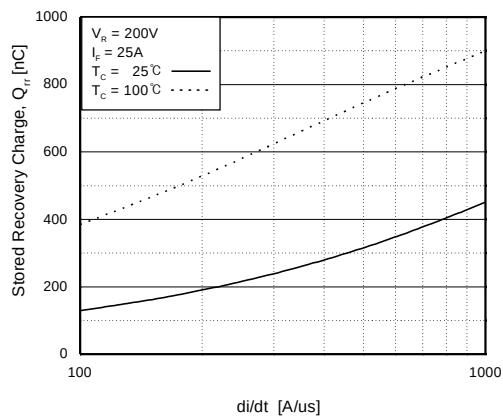


Fig 20. Stored Charge

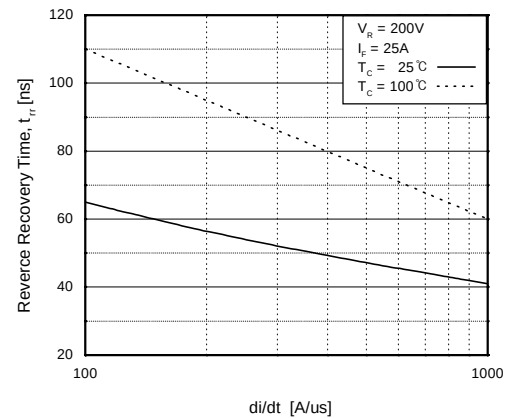
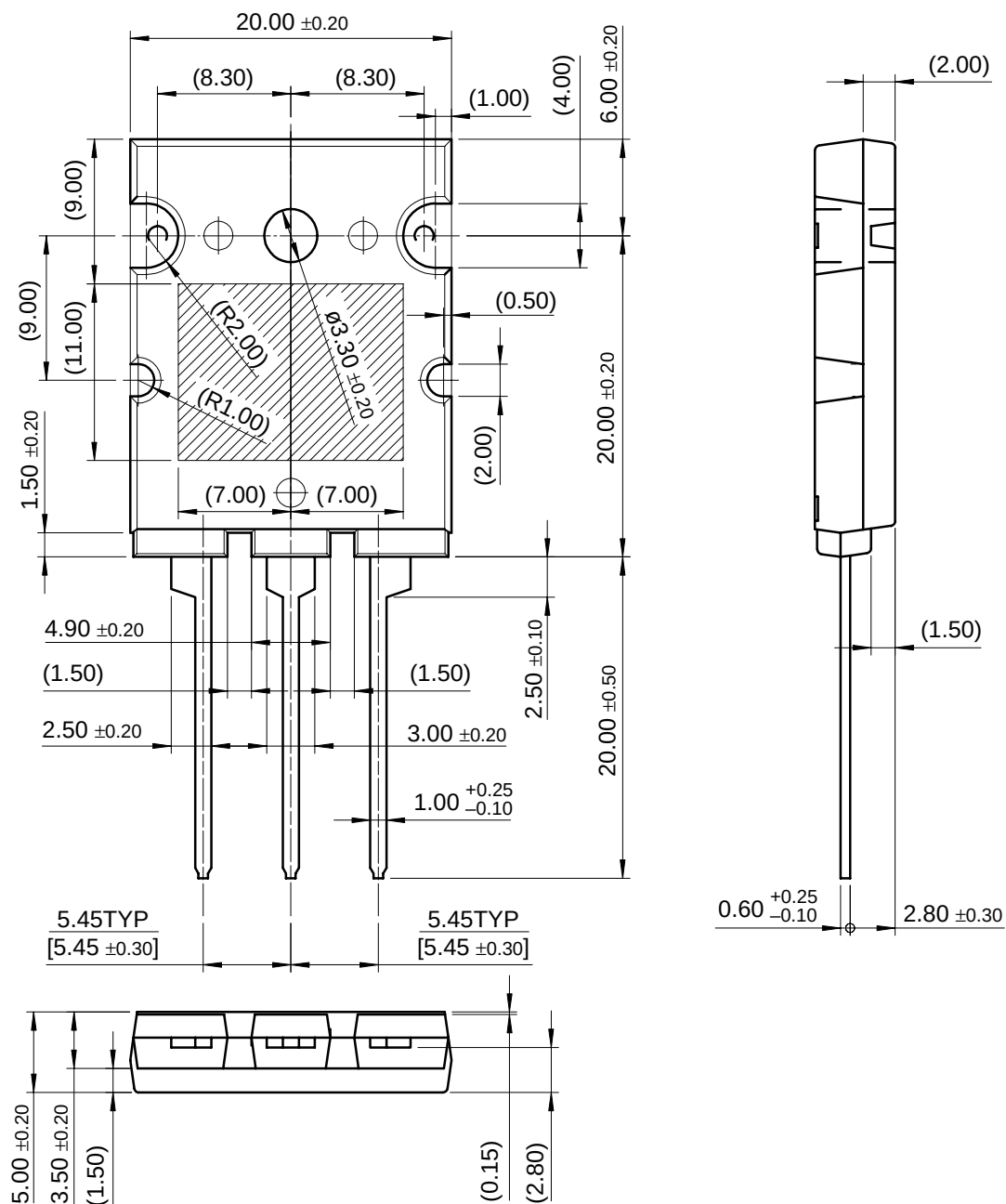


Fig 21. Reverse Recovery Time



HSGL160N60UFDTU
Ultrafast IGBT

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